



Material Content Data Sheet



Sales Product Name		BC 858BW H6327		Issued		26. September 2017		
MA#		MA000845534						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.08		769	
	non noble metal	arsenic	7440-38-2	0.000	0.00		8	
	inorganic material	silicon	7440-21-3	0.039	0.66	0.74	6569	7346
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1323	
	non noble metal	copper	7440-50-8	2.617	43.90	44.08	439176	441028
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	853	853
encapsulation	organic material	carbon black	1333-86-4	0.031	0.53		5268	
	plastics	epoxy resin	-	0.675	11.33		113267	
	inorganic material	silicondioxide	60676-86-0	2.433	40.83	52.69	408288	526823
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22270	22270
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1680	1680
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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